



## MOSFETs Silicon 430V N-Channel MOS

**■ Applications**

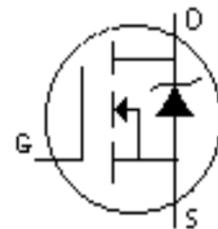
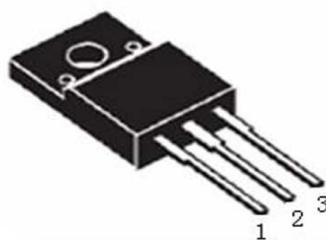
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

**■ Features**

- Low  $R_{DS(ON)}$
- Ultra Low Gate Charge
- RoHS Compliant
- 100% UIS and RG Tested

**■ Product Summary**

$V_{DS}$	430	V
$I_D$	11	A
$R_{DS(ON)} \text{ ,Typ@10V}$	0.47	$\Omega$
$Q_g$	20	nC



Gate: 1  
Drain: 2  
Source: 3

TO-220F

Marking	Package	Packaging	Min. package quantity
MFIRF11N45	TO-220F	Tube	1000





### ■ Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	430	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current $T_c=25^\circ\text{C}$ (Note 1)	$I_D$	11	A
Continuous Drain Current $T_c=100^\circ\text{C}$ (Note 1)		6.8	
Drain Current-Pulsed (Note 1)	$I_{DM}$	44	A
Total Dissipation	$P_D$	50	W
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55-150	$^\circ\text{C}$
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	450	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

### ■ Thermal Characteristics

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	$R_{\theta JC}$	2.5	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$

Note 1: Ensure that the channel temperature does not exceed  $150^\circ\text{C}$ .

Note 2:  $V_{DD}=50\text{V}$ ,  $T_{ch}=25^\circ\text{C}$ (initial),  $I_{AS}=11\text{A}$ ,  $R_g=25\Omega$ .

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





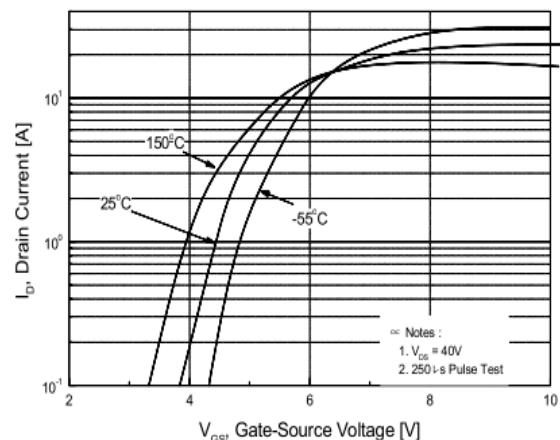
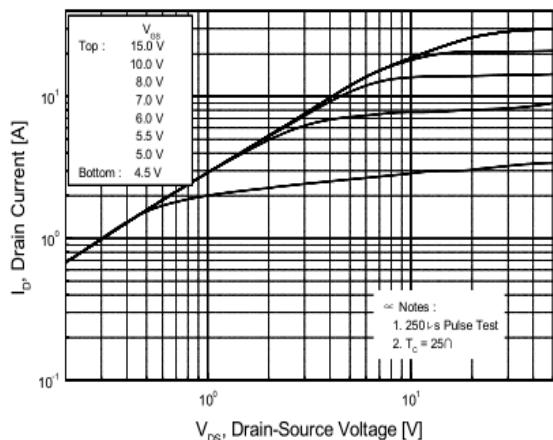
■ Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	430	-	-	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =430V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	3	4	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.5A	-	0.47	0.5	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	1120	-	pF
Output Capacitance	C <sub>oss</sub>		-	118	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	2	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =250V, I <sub>D</sub> =11A, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω	-	32	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	28	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	90	-	ns
Turn-Off Rise Time	t <sub>f</sub>		-	50	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =320V, I <sub>D</sub> =11A, V <sub>GS</sub> =10V	-	20	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	6.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	4.5	-	nC
<b>Source-Drain Characteristics</b>						
Max. Diode Forward Cuurent	I <sub>S</sub>		-	-	11	A
Max. Pulsed Forward Cuurent	I <sub>SM</sub>		-	-	44	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =11A	-	0.86	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =320V, I <sub>F</sub> =11A, di/dt=100A/us	-	320	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	3.2	-	μC



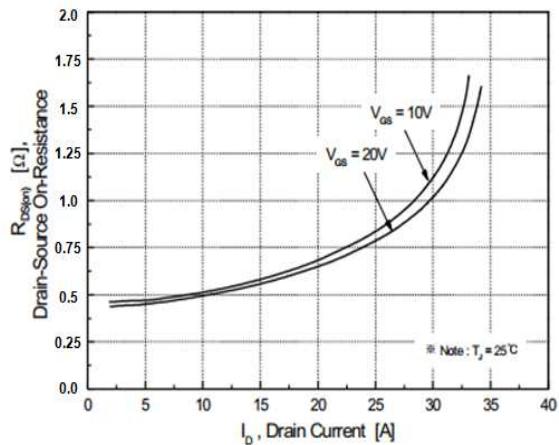


## ■ Characteristics Curves

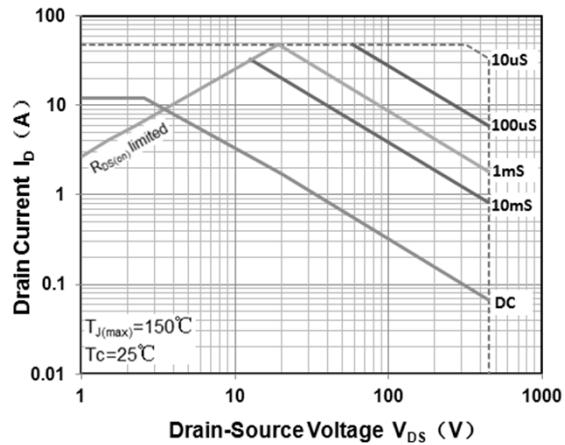


Output Characteristics

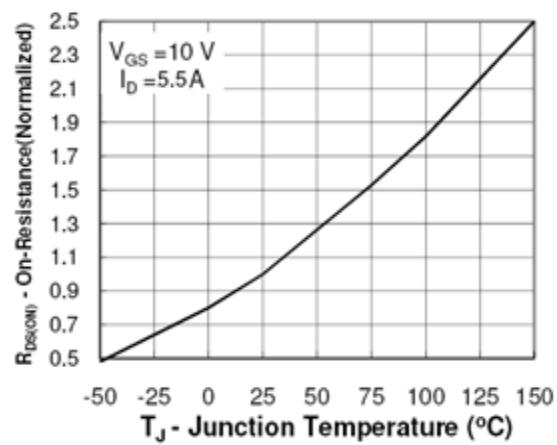
Transfer Characteristics



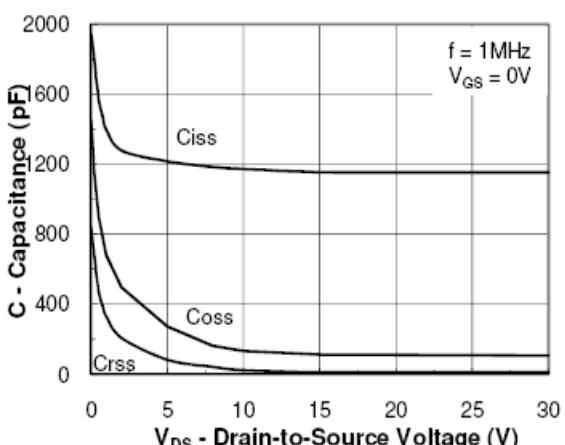
On Resistance Vs Drain Current



Safe Operating Area

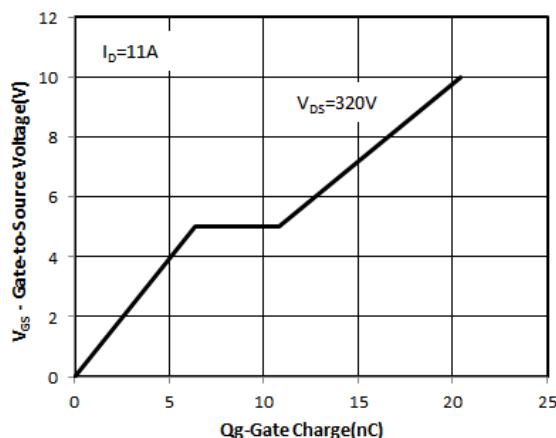


Rdson-JunctionTemperature

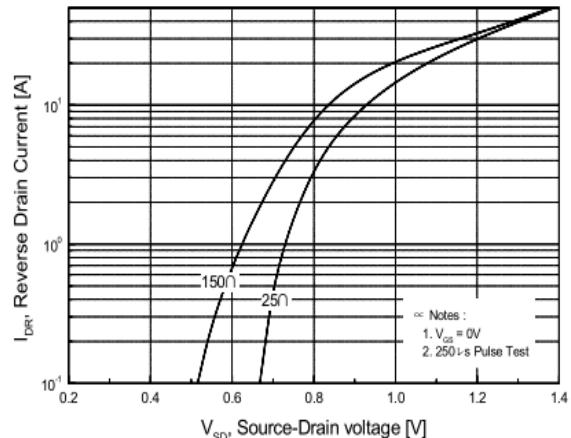


Capacitance

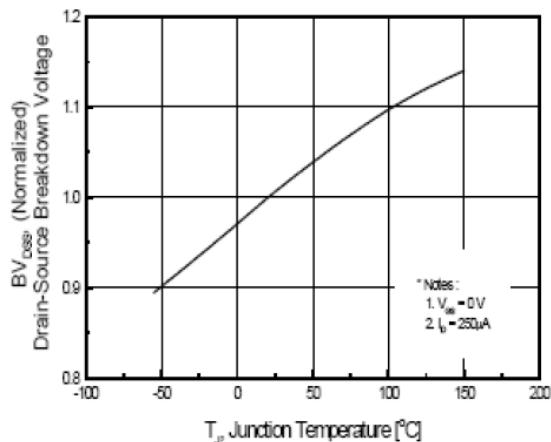




Gate Charge Waveform



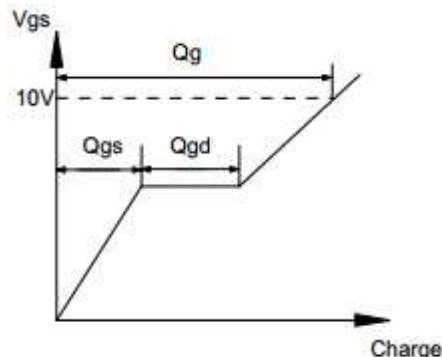
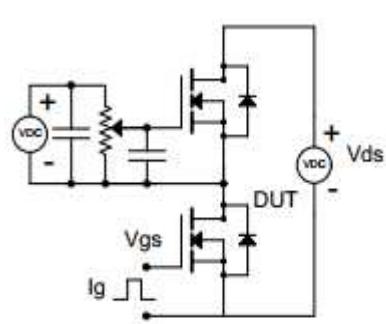
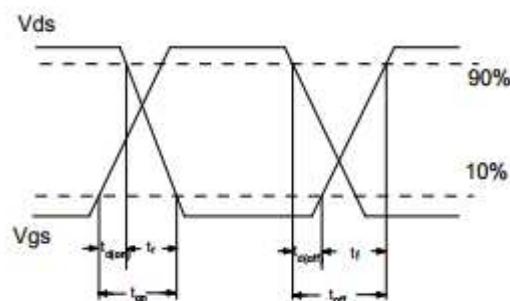
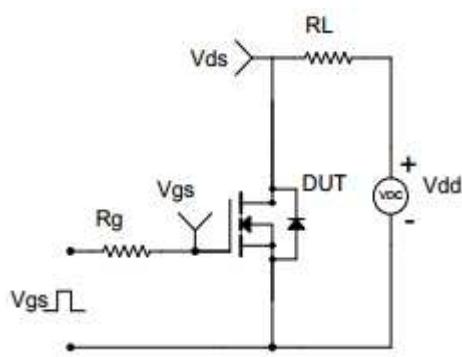
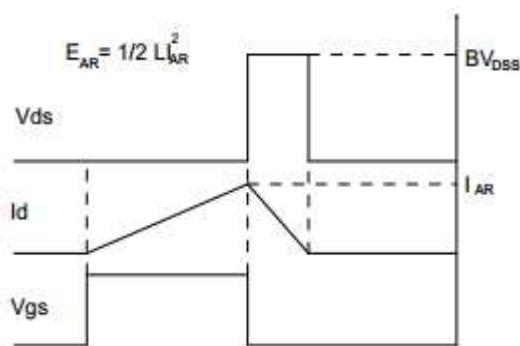
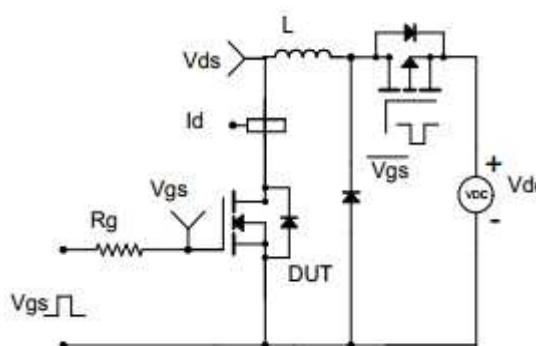
Source-Drain Diode Forward Voltage



Breakdown Voltage Vs Junction Temperature

Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



**■ Test Circuit & Waveform****Gate Charge Test Circuit & Waveform****Resistive Switching Test Circuit & Waveform****Unclamped Inductive Switching (UIS) Test Circuit & Waveform**



## ■ TO-220F Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	4.5		4.9	E1	6.5	7	7.5
A1	2.3		2.9	e	2.44	2.54	2.64
b	0.65		0.9	L	12.5		14.3
b1	1.1		1.7	L1	9.45		10.05
b2	1.2		1.4	L2	15		16
c	0.35		0.65	L3	3.2		4.4
D	14.5		16.5	ΦP	3		3.3
D1	6.1		6.9	Q	2.5		2.9
E	9.6		10.3				

